Project	: System:	Sub-system:
Unit Code:	Rev. No:	Date:
	Photograph of the un	it with lids closed
	(lids not applicable in case of	of PCB alone)

Project :	System:	Sub-system:	
Unit Code:	Rev. No:	Date:	
	Photograph of the u	nit with lids open (Top View)	
	(lids not applica	able in case of PCB alone)	
			¬
	Photograph of the unit with	n lids open (Bottom View)	
	(lids not applicable i	n case of PCB alone)	

Circuit Diagram (Schematic):				
Project :	System:	Sub-system:		
•	•	Š		
Unit Code:	Rev. No:	Date:		

Un	it Code:		R	ev. No:		Date:		
	Bill of Materials							
	1. Parts Li	st						
Circuit symbol	Package style	Type/ Value	Tolerance	Ratings	Procurement information		Manufacturer/Vendor	Remarks

Sub-system:

System:

Project :

Project :	System:	Sub-system:	
Unit Code:	Rev. No:	Date:	

Bill of Materials

2. Materials List

- 1. Substrate material: Details, manufacturer, size and conductor plating information.
- 2. Connectors: Type, Part No., Manufacturer and quantity
- 3. Fasteners, nuts, washers: Material, size and quantity
- 4. Solder lead: Details
- 5. Chassis: Material, Size, type, surface finish and drawing. (Drawing must be attached.)

Project	:	System:	Sub-system:
Unit Code:		Rev. No:	Date:

Circuit Layout

Layout file details (like filename, folder etc)

Copy of the layout (top, bottom and drill details): Attach hard copy

Component placement diagram

Project :	System:	Sub-system:		
Unit Code:	Rev. No:	Date:		
	Test and Evaluation			
Unit Serial No:				
Test Plots: Hard copies to be attached				
Test results in tabular format (e.g. parameters, specifications and results)				
Signature				
Date:				
Test Plots: Hard copies to be a Test results in tabular format (e		ations and results)		